

What is claimed is:

1. A leadframe to be used in a semiconductor device,
which comprises a plurality of parallel first
leads and a plurality of parallel second leads,
wherein the pitch of the first leads is different
from that of the second leads, and the first leads
are joined end-to-end with the second leads.
2. The leadframe according to claim 1,
wherein at least either of the first leads or the
second leads have their thickness reduced.
3. A method for manufacturing a semiconductor device
using a leadframe,
which comprises the steps of mounting a semi-
conductor element on the leadframe according to claim
1, and encapsulating the semiconductor element in
a package,
wherein the dimension of the package for en-
capsulation is set such that at least either of the
first leads or the second leads project from the
package.
4. The method for manufacturing a semiconductor device
using a leadframe, according to claim 3,

wherein at least either of the first leads or the second leads are squeezed by a mold for molding the package and have their thickness reduced.

5. A semiconductor device using the leadframe according to claim 1.

6. An electronic equipment using the semiconductor device according to claim 5.